

SMIC SENJU SOLDER (PHILS.) INC.

BLOCK 9 LOT 6 PHASE 1 PEZA ROSARIO, CAVITE
 TEL. NO. (046) 437-0240; 437-2720 to 22
 FAX NO. (046)437-0239; E-MAIL ADDRESS: sspi@senju.ph

DOCUMENT NUMBER

F2-5-L301-003

REVISION NUMBER

9.0

PAGE NUMBER

1 OF 5

PRODUCT NAME

BAR SOLDER H63A

1.0 SCOPE

This specification describes the product specification for Bar Solder H63A used for wiring connection, etc. of electrical and electronics parts among others.

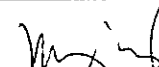

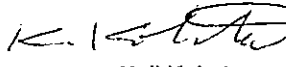
2.0 PRODUCT SPECIFICATION

2.1 Chemical Composition of solder (Test method: STM-9)
 Specified in JIS Z 3282:2006 Grade A

| Composition (wt %) | |
|--------------------|---------|
| Sn | Pb |
| 62.5 ~ 63.5 | Balance |

| Impurity (wt %) | | | | | | | | | | | |
|-----------------|---------|------|------|------|-------|-------|------|------|------|------|------|
| Less than | Maximum | | | | | | | | | | |
| Cd | Sb | Cu | Bi | Fe | Zn | Al | As | Ag | Au | In | Ni |
| 0.002 | 0.20 | 0.08 | 0.10 | 0.02 | 0.001 | 0.001 | 0.03 | 0.10 | 0.05 | 0.10 | 0.01 |

APPROVAL

| | | |
|--|--|--|
|  Mabel Clave-Gianan QC Section Head |  Naoyuki Shirase Asst. Production Manager |  Koji Kohata Vice-President |
|--|--|--|

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PRODUCT NAME

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2.2 Physical Properties of Solder (JIS Z 3282)

| Symbol | Melting Temperature Range (C) | | Specific Gravity |
|-------------|---------------------------------|-------------|------------------|
| | Solidus | Liquidus | |
| H63A | 183 approx. | 183 approx. | Approx. 8.4 |

2.3 Shape, Size, Weight, etc.

| Shape | Size (mm) Width x Length x Height | Weight/piece |
|------------------|--------------------------------------|--------------|
| Hand Casting Bar | 20 mm x 400 mm x 7 mm. Approx. | Approx. 500g |

2.4 Appearance (Test Method: STM-1)

- 2.4.1 The surface shall be free from any noticeable defective gloss, adhesion of foreign matters or soil.
- 2.4.2 No noticeable scratch, crack or fissure is permissible.
- 2.4.3 Surface oxidation and mixture of oxide is not permissible.

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PRODUCT NAME

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3.0 TEST REPORT

3.1 Test report on the item specified below shall be issued for every production lot and attached with the shipment of the lot.

3.1.1 Chemical composition and impurities of solder (Test Method : STM-9)

4.0 PACKAGING PRESENTATION

4.1 Packaging

| Item Packing | Outer Packing | Packed Quantity | Net Weight | Color of seal tape |
|--------------|---|---------------------------|------------------|--------------------|
| Bare | Corrugated Paper box with blue printing | Approx. 40 pieces per box | 20.01 ~ 20.06kgs | Blue |

4.2 Marking

| Presentation on Solder Surface |
|-----------------------------------|
| 1. Company Name – e.g. Senju Phil |
| 2. Product Type – e.g. H63A |

| Presentation on outer Packing | Product Label |
|--|--|
| 1. Product Name – Bar Solder Product symbol – e.g. H63A | <p>Product Name: BAR SOLDER H63A Composition: Sn63Pb37 Size: 20 mm x 400 mm x 7 mm Lot No.: F0929-841 Manufacture Date: September 29, 2009 Net Weight: 20 kgs. Validity: September 29, 2013</p> |
| 2. Composition | |
| 3. Size | |
| 4. Lot No. | |
| 5. Manufacture Date | |
| 6. Net Weight | |
| 7. Validity | |
| 8. Company Name | |
| 9. Company Address | |
| 10. QC Passed (found @ the box) | |

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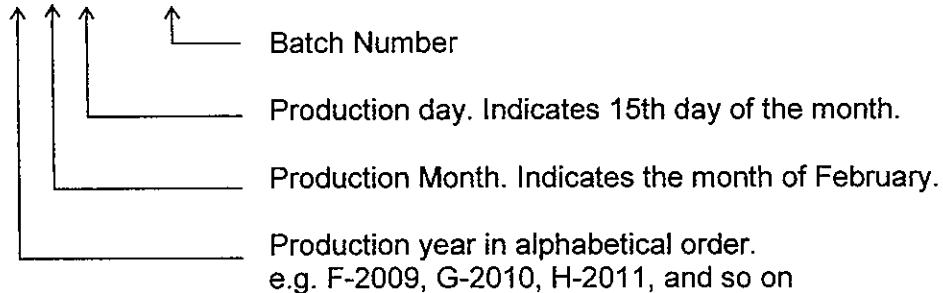
PRODUCT NAME

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5.0 COMPOSITION OF LOT NUMBER

e.g.

F 02 15 - 640



6.0 GUARANTEE PERIOD

The guarantee period shall be 4 years from the production date (Lot No).

7.0 STORAGE AND HANDLING PRECAUTIONS

- 7.1 Ordinary storing will pose no problem. Attention should be given to deposition of water and moisture which may be due to sweating caused by the stoppage of an air conditioner in the night time, among others, and also refrain from placing it in an acidic environment.
- 7.2 Dry well the solder before usage to prevent possible splashing or spattering of solder when heated due to deposition of water.

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8.0 TEST METHOD

STM-1 Appearance

Appearance will be inspected by visual observation as to the items specified by the applicable standard.

STM-2 Unit Weight

Weighing will be performed using a weighing apparatus having a minimum graduation less than 5/10000 of the maximum weighing capacity.

STM-3 Size

Measurement will be taken using calipers stipulated in JIS B7507 outer micrometer stipulated in JIS B7502, or, any other suitable measuring apparatus.

STM-9 Chemical Composition of Solder

Solder analysis method according to JIS Z 3910, or, the general rules of Emission Spectral Analysis method according to JIS K 0116 will be followed, provided, however, that Silver Solder Analysis Method according to JIS Z 3901 will be used for determining the content of blended Ag(Silver).

9.0 OTHERS

9.1 The quality of this product conforms to JIS Z 3282 Grade A Standard.

9.2 Any disputes arise concerning the industrial property of the said product infringement thereof, etc. shall be disposed off and settled by our company on our own responsibility.

9.3 In case any doubt arise about the quality of the product after its delivery, both companies shall consult with each other to settle the matter.

9.4 Your company is requested not to divulge or disclosed to any other companies, or publicize, any matter relating to this specification.

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